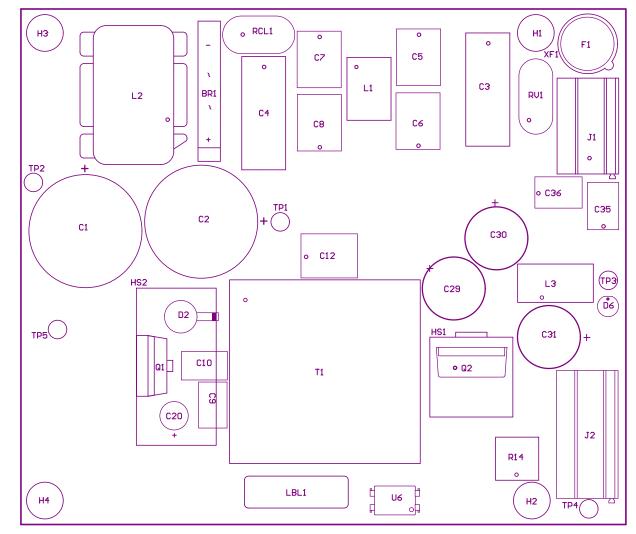
ZZI Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

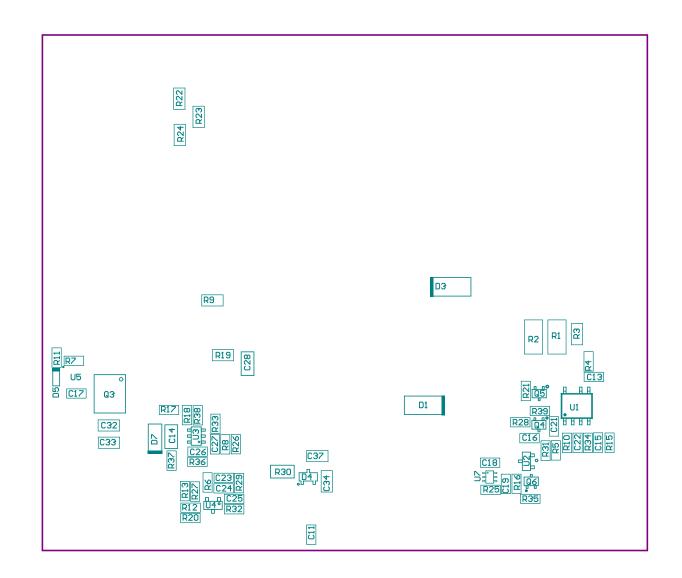
ZZ2 These assemblies are ESD sensitive, ESD precautions shall be observed.

- ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- ZZ4 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE		BOARD #: T	IDA-00702	REV: RevB	SVN REV	Not In VersionControl
IGNORE ->	M5 Assembly Top					
PLOT NAME =	Top Assembly Drawing	GENERATED	: 12/3/20	015 5:28:54	PM	TEXAS INSTRUMENTS



## COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-00702	REV: RevB	SVN REV: Not	In VersionControl		
	IGNORE -> M6 Assembly Bottom					
PLOT NAME = Bottom Assembly Drawing	GENERATED : 12/3/2	2015 5: 28: 54	PM	TEXAS INSTRUMENTS		

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